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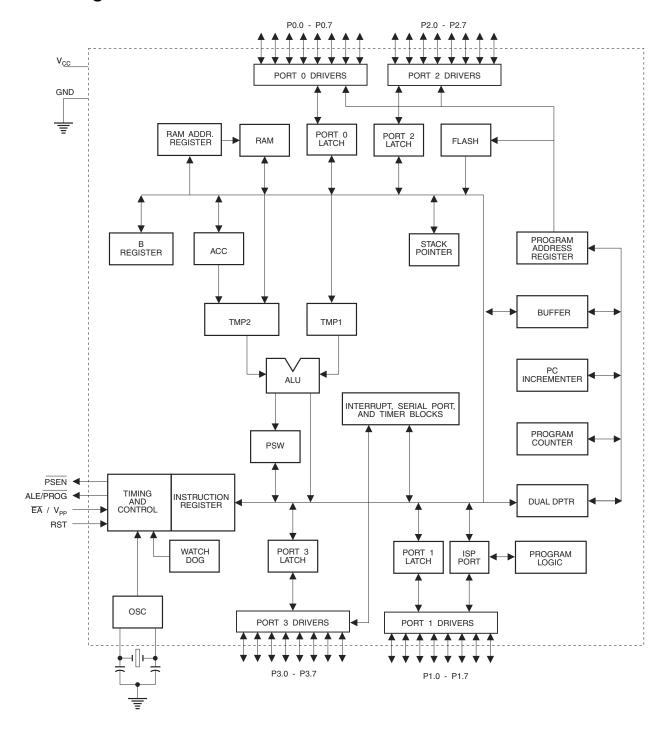
What is "Embedded - Microcontrollers"?

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Applications of "<u>Embedded - Microcontrollers</u>"

Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89ls52-16aur
Supplier Device Package	44-TQFP (10x10)
Package / Case	44-TQFP
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Oscillator Type	Internal
Data Converters	-
Voltage - Supply (Vcc/Vdd)	2.7V ~ 4V
RAM Size	256 x 8
EEPROM Size	-
Program Memory Type	FLASH
Program Memory Size	8KB (8K x 8)
Number of I/O	32
Peripherals	WDT
Connectivity	UART/USART
Speed	16MHz
Core Size	8-Bit
Core Processor	8051
Product Status	Active
Details	

# 3. Block Diagram





### 4. Pin Description

4.1 VCC

Supply voltage.

4.2 GND

Ground.

#### 4.3 Port 0

Port 0 is an 8-bit open drain bi-directional I/O port. As an output port, each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pull-ups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. **External pull-ups are required during program verification.** 

#### 4.4 Port 1

Port 1 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current  $(I_{IL})$  because of the internal pull-ups.

In addition, P1.0 and P1.1 can be configured to be the timer/counter 2 external count input (P1.0/T2) and the timer/counter 2 trigger input (P1.1/T2EX), respectively, as shown in the following table.

Port 1 also receives the low-order address bytes during Flash programming and verification.

Port Pin	Alternate Functions
P1.0	T2 (external count input to Timer/Counter 2), clock-out
P1.1	T2EX (Timer/Counter 2 capture/reload trigger and direction control)
P1.5	MOSI (used for In-System Programming)
P1.6	MISO (used for In-System Programming)
P1.7	SCK (used for In-System Programming)

#### 4.5 Port 2

Port 2 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current ( $I_{II}$ ) because of the internal pull-ups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

 Table 5-1.
 AT89LS52 SFR Map and Reset Values

			•						
0F8H									0FFH
0F0H	B 00000000								0F7H
0E8H									0EFH
0E0H	ACC 00000000								0E7H
0D8H									0DFH
0D0H	PSW 00000000								0D7H
0C8H	T2CON 00000000	T2MOD XXXXXX00	RCAP2L 00000000	RCAP2H 00000000	TL2 00000000	TH2 00000000			0CFH
0C0H									0C7H
0B8H	IP XX000000								0BFH
0B0H	P3 11111111								0B7H
0A8H	IE 0X000000								0AFH
0A0H	P2 11111111		AUXR1 XXXXXXX0				WDTRST XXXXXXXX		0A7H
98H	SCON 00000000	SBUF XXXXXXXX							9FH
90H	P1 11111111								97H
88H	TCON 00000000	TMOD 00000000	TL0 00000000	TL1 00000000	TH0 00000000	TH1 00000000	AUXR XXX00XX0		8FH
80H	P0 11111111	SP 00000111	DP0L 00000000	DP0H 00000000	DP1L 00000000	DP1H 00000000		PCON 0XXX0000	87H



## Table 5-2. T2CON – Timer/Counter 2 Control Register

T2CON	T2CON Address = 0C8H Reset Value = 0000 0000B										
Bit Add	ressable										
D:	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2			
Bit	7	6	5	4	3	2	1	0			

Symbol	Function
TF2	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK = 1 or TCLK = 1.
EXF2	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	Receive clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in serial port Modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.
TCLK	Transmit clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in serial port Modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	Timer 2 external enable. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	Start/Stop control for Timer 2. TR2 = 1 starts the timer.
C/T2	Timer or counter select for Timer 2. $C/\overline{T2} = 0$ for timer function. $C/\overline{T2} = 1$ for external event counter (falling edge triggered).
CP/RL2	Capture/Reload select. $CP/\overline{RL2} = 1$ causes captures to occur on negative transitions at T2EX if EXEN2 = 1. $CP/\overline{RL2} = 0$ causes automatic reloads to occur when Timer 2 overflows or negative transitions occur at T2EX when EXEN2 = 1. When either RCLK or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

Table 5-3. AUXR: Auxiliary Register

AUXR	Address	Address = 8EH Reset Value = XXX00XX0B											
	Not Bit A	Addressable											
		_	-	_	_	DISALE	İ						
	Bit	7	6	5	4	3	2	1	0	İ			
_	Reserved for	leserved for future expansion											
DISALE	Disable/Enal	Disable/Enable ALE											
	DISALE	ALE Operating Mode											
	0	ALE is em	ALE is emitted at a constant rate of 1/6 the oscillator frequency										
	1	ALE is act	ive only dur	ing a MOV	or MOVC ir	struction							
DISRTO	Disable/Enal	ole Reset ou	ıt										
	DISRTO												
	0	Reset pin	is driven Hi	gh after WD	T times out								
	1	Reset pin	is input only	,									
WDIDLE	Disable/Enal	ole WDT in I	DLE mode										
	WDIDLE												
	0	WDT cont	inues to cou	ınt in IDLE ı	mode								
	1	WDT halts	counting in	IDLE mode	е								

**Dual Data Pointer Registers:** To facilitate accessing both internal and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR AUXR1 selects DP0 and DPS = 1 selects DP1. The user should **always** initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

**Power Off Flag:** The Power Off Flag (POF) is located at bit 4 (PCON.4) in the PCON SFR. POF is set to "1" during power up. It can be set and rest under software control and is not affected by reset.





Table 5-4. AUXR1: Auxiliary Register 1

AUXR1	Address	= A2H				Reset Value = XXXXXXX0B						
	Not Bit A	Not Bit Addressable										
		_	_	_	_	_	_	DPS				
	Bit	7	6	5	4	3	2	1	0			
-	Reserved for	future expa	ansion									
DPS	Data Pointer	Register Se	elect									
	DPS											
	0	0 Selects DPTR Registers DP0L, DP0H										
	1	Selects D	PTR Regist	ers DP1L, D	P1H							

### Memory Organization

MCS-51 devices have a separate address space for Program and Data Memory. Up to 64K bytes each of external Program and Data Memory can be addressed.

### 6.1 Program Memory

If the  $\overline{EA}$  pin is connected to GND, all program fetches are directed to external memory.

On the AT89LS52, if  $\overline{\text{EA}}$  is connected to  $V_{\text{CC}}$ , program fetches to addresses 0000H through 1FFFH are directed to internal memory and fetches to addresses 2000H through FFFFH are directed to external memory.

### 6.2 Data Memory

The AT89LS52 implements 256 bytes of on-chip RAM. The upper 128 bytes occupy a parallel address space to the Special Function Registers. This means that the upper 128 bytes have the same addresses as the SFR space but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the address mode used in the instruction specifies whether the CPU accesses the upper 128 bytes of RAM or the SFR space. Instructions which use direct addressing access of the SFR space.

For example, the following direct addressing instruction accesses the SFR at location 0A0H (which is P2).

MOV 0A0H, #data

Instructions that use indirect addressing access the upper 128 bytes of RAM. For example, the following indirect addressing instruction, where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

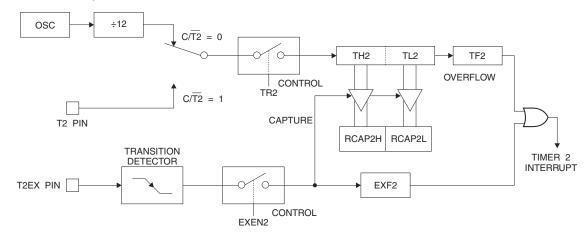
MOV @RO, #data

Note that stack operations are examples of indirect addressing, so the upper 128 bytes of data RAM are available as stack space.

#### 10.1 Capture Mode

In the capture mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 is a 16-bit timer or counter which upon overflow sets bit TF2 in T2CON. This bit can then be used to generate an interrupt. If EXEN2 = 1, Timer 2 performs the same operation, but a 1-to-0 transition at external input T2EX also causes the current value in TH2 and TL2 to be captured into RCAP2H and RCAP2L, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set. The EXF2 bit, like TF2, can generate an interrupt. The capture mode is illustrated in Figure 10-1.

Figure 10-1. Timer in Capture Mode



### 10.2 Auto-reload (Up or Down Counter)

Timer 2 can be programmed to count up or down when configured in its 16-bit auto-reload mode. This feature is invoked by the DCEN (Down Counter Enable) bit located in the SFR T2MOD (see Table 10-2). Upon reset, the DCEN bit is set to 0 so that timer 2 will default to count up. When DCEN is set, Timer 2 can count up or down, depending on the value of the T2EX pin.

Figure 10-2 shows Timer 2 automatically counting up when DCEN=0. In this mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 counts up to 0FFFFH and then sets the TF2 bit upon overflow. The overflow also causes the timer registers to be reloaded with the 16-bit value in RCAP2H and RCAP2L. The values in Timer in Capture ModeRCAP2H and RCAP2L are preset by software. If EXEN2 = 1, a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at external input T2EX. This transition also sets the EXF2 bit. Both the TF2 and EXF2 bits can generate an interrupt if enabled.

Setting the DCEN bit enables Timer 2 to count up or down, as shown in Figure 10-2. In this mode, the T2EX pin controls the direction of the count. A logic 1 at T2EX makes Timer 2 count up. The timer will overflow at 0FFFFH and set the TF2 bit. This overflow also causes the 16-bit value in RCAP2H and RCAP2L to be reloaded into the timer registers, TH2 and TL2, respectively.

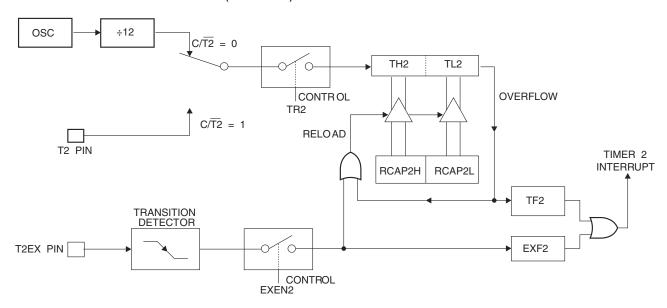
A logic 0 at T2EX makes Timer 2 count down. The timer underflows when TH2 and TL2 equal the values stored in RCAP2H and RCAP2L. The underflow sets the TF2 bit and causes 0FFFFH to be reloaded into the timer registers.

The EXF2 bit toggles whenever Timer 2 overflows or underflows and can be used as a 17th bit of resolution. In this operating mode, EXF2 does not flag an interrupt.





**Figure 10-2.** Timer 2 Auto Reload Mode (DCEN = 0)



**Table 10-2.** T2MOD – Timer 2 Mode Control Register

T2MOE	O Address = 0	C9H			Re	eset Value = X	XXX XX00B	
Not Bit Addressable								
	_	_	_	_	_	_	T2OE	DCEN
Bit	7	6	5	4	3	2	1	0

Symbol	Function
_	Not implemented, reserved for future
T2OE	Timer 2 Output Enable bit
DCEN	When set, this bit allows Timer 2 to be configured as an up/down counter



### 13. Interrupts

The AT89LS52 has a total of six interrupt vectors: two external interrupts (INT0 and INT1), three timer interrupts (Timers 0, 1, and 2), and the serial port interrupt. These interrupts are all shown in Figure 13-1.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 13-1 shows that bit position IE.6 is unimplemented. User software should not write 1 to this bit position, since it may be used in future AT89 products.

Timer 2 interrupt is generated by the logical OR of bits TF2 and EXF2 in register T2CON. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and that bit will have to be cleared in software.

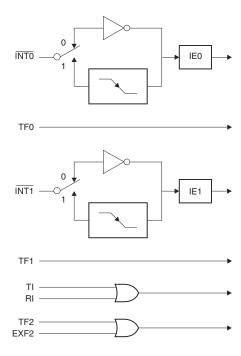
The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle. However, the Timer 2 flag, TF2, is set at S2P2 and is polled in the same cycle in which the timer overflows.

Table 13-1. Interrupt Enable (IE) Register

(MSB)				(LSE	3)		
EA	-	ET2	ES	ET1	EX1	ET0	EX0
Enable Bit	= 1 enables the	e interrupt.	·		·		
Enable Bit	= 0 disables the	e interrupt.					

Symbol	Position	Function
EA	IE.7	Disables all interrupts. If EA = 0, no interrupt is acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
_	IE.6	Reserved.
ET2	IE.5	Timer 2 interrupt enable bit.
ES	IE.4	Serial Port interrupt enable bit.
ET1	IE.3	Timer 1 interrupt enable bit.
EX1	IE.2	External interrupt 1 enable bit.
ET0	IE.1	Timer 0 interrupt enable bit.
EX0	IE.0	External interrupt 0 enable bit.
User software should i	never write 1s to reserve	ed bits, because they may be used in future AT89 products.

Figure 13-1. Interrupt Sources



### 14. Oscillator Characteristics

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 16-1. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 16-2. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

#### 15. Idle Mode

In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special functions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

Note that when idle mode is terminated by a hardware reset, the device normally resumes program execution from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle mode is terminated by a reset, the instruction following the one that invokes idle mode should not write to a port pin or to external memory.

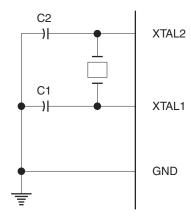




#### 16. Power-down Mode

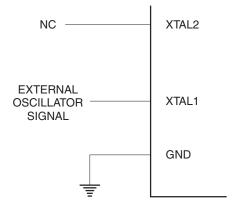
In the Power-down mode, the oscillator is stopped, and the instruction that invokes Power-down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power-down mode is terminated. Exit from Power-down mode can be initiated either by a hardware reset or by activation of an enabled external interrupt ( $\overline{\text{INT0}}$ ). Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before  $V_{CC}$  is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Figure 16-1. Oscillator Connections



Note: C1, C2 = 30 pF  $\pm$  10 pF for Crystals = 40 pF  $\pm$  10 pF for Ceramic Resonators

Figure 16-2. External Clock Drive Configuration





Data Polling: The AT89LS52 features Data Polling to indicate the end of a byte write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written data on P0.7. Once the write cycle has been completed, true data is valid on all outputs, and the next cycle may begin. Data Polling may begin any time after a write cycle has been initiated.

**Ready/Busy:** The progress of byte programming can also be monitored by the RDY/BSY output signal. P3.0 is pulled low after ALE goes high during programming to indicate BUSY. P3.0 is pulled high again when programming is done to indicate READY.

**Program Verify:** If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. **The status of the individual lock bits can be verified directly by reading them back**.

**Reading the Signature Bytes:** The signature bytes are read by the same procedure as a normal verification of locations 000H, 100H, and 200H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows.

(000H) = 1EH indicates manufactured by Atmel (100H) = 62H indicates 89LS52 (200H) = 06H

**Chip Erase:** In the parallel programming mode, a chip erase operation is initiated by using the proper combination of control signals and by pulsing ALE/PROG low for a duration of 200 ns - 500 ns.

In the serial programming mode, a chip erase operation is initiated by issuing the Chip Erase instruction. In this mode, chip erase is self-timed and takes about 500 ms.

During chip erase, a serial read from any address location will return 00H at the data output.

# 19. Programming the Flash – Serial Mode

The Code memory array can be programmed using the serial ISP interface while RST is pulled to  $V_{\text{CC}}$ . The serial interface consists of pins SCK, MOSI (input) and MISO (output). After RST is set high, the Programming Enable instruction needs to be executed first before other operations can be executed. Before a reprogramming sequence can occur, a Chip Erase operation is required.

The Chip Erase operation turns the content of every memory location in the Code array into FFH.

Either an external system clock can be supplied at pin XTAL1 or a crystal needs to be connected across pins XTAL1 and XTAL2. The maximum serial clock (SCK) frequency should be less than 1/16 of the crystal frequency. With a 16 MHz oscillator clock, the maximum SCK frequency is 1 MHz.

#### 19.1 Serial Programming Algorithm

To program and verify the AT89LS52 in the serial programming mode, the following sequence is recommended:

- 1. Power-up sequence:
  - a. Apply power between VCC and GND pins.
  - b. Set RST pin to "H".

If a crystal is not connected across pins XTAL1 and XTAL2, apply a 3 MHz to 16 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.

- 2. Enable serial programming by sending the Programming Enable serial instruction to pin MOSI/P1.5. The frequency of the shift clock supplied at pin SCK/P1.7 needs to be less than the CPU clock at XTAL1 divided by 16.
- 3. The Code array is programmed one byte at a time in either the Byte or Page mode. The write cycle is self-timed and typically takes less than 1 ms at 2.7V.
- 4. Any memory location can be verified by using the Read instruction which returns the content at the selected address at serial output MISO/P1.6.
- 5. At the end of a programming session, RST can be set low to commence normal device operation.

Power-off sequence (if needed):

- 1. Set XTAL1 to "L" (if a crystal is not used).
- 2. Set RST to "L".
- 3. Turn V<sub>CC</sub> power off.

**Data Polling:** The Data Polling feature is also available in the serial mode. In this mode, during a byte write cycle an attempted read of the last byte written will result in the complement of the MSB of the serial output byte on MISO.

#### 19.2 Serial Programming Instruction Set

The Instruction Set for Serial Programming follows a 4-byte protocol and is shown in Table 22-1.





## 20. Programming Interface - Parallel Mode

Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most major worldwide programming vendors offer worldwide support for the Atmel microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Table 20-1. Flash Programming Modes

				ALE/	EA/						P0.7-0	P2.4-0	P1.7-0
Mode	$v_{cc}$	RST	PSEN	PROG	V <sub>PP</sub>	P2.6	P2.7	P3.3	P3.6	P3.7	Data	Add	ress
Write Code Data	5V	Н	L	(2)	12V	L	Н	Н	Н	Н	D <sub>IN</sub>	A12-8	A7-0
Read Code Data	5V	Н	L	Н	Н	L	L	L	Н	Н	D <sub>OUT</sub>	A12-8	A7-0
Write Lock Bit 1	5V	Н	L	(3)	12V	Н	Н	Н	Н	Н	Х	Х	Х
Write Lock Bit 2	5V	Н	L	(3)	12V	Н	Н	Н	L	L	Х	Х	х
Write Lock Bit 3	5V	Н	L	(3)	12V	Н	L	Н	Н	L	Х	х	х
Read Lock Bits 1, 2, 3	5V	Н	L	Н	Н	Н	Н	L	Н	L	P0.2, P0.3, P0.4	х	x
Chip Erase	5V	Н	L	(1)	12V	Н	L	Н	L	L	Х	Х	х
Read Atmel ID	5V	Н	L	Н	Н	L	L	L	L	L	1EH	X 0000	00H
Read Device ID	5V	Н	L	Н	Н	L	L	L	L	L	62H	X 0001	00H
Read Device ID	5V	Н	L	Н	Н	L	L	L	L	L	06H	X 0010	00H

Notes: 1. Each PROG pulse is 200 ns - 500 ns for Chip Erase.

<sup>2.</sup> Each PROG pulse is 200 ns - 500 ns for Write Code Data.

<sup>3.</sup> Each PROG pulse is 200 ns - 500 ns for Write Lock Bits.

<sup>4.</sup> RDY/BSY signal is output on P3.0 during programming.

<sup>5.</sup> X = don't care.



Table 22-1. Serial Programming Instruction Set

	Instruction Format				
Instruction	Byte 1	Byte 2	Byte 3	Byte 4	Operation
Programming Enable	1010 1100	0101 0011	xxxx xxxx	xxxx xxxx 0110 1001 (Output on MISO)	Enable Serial Programming while RST is high
Chip Erase	1010 1100	100x xxxx	xxxx xxxx	xxxx xxxx	Chip Erase Flash memory array
Read Program Memory (Byte Mode)	0010 0000	XXX 5 1 1 0 8 8 8 8 8	A A A A A A A A A A A A A A A A A A A	D2 D2 D2 D2	Read data from Program memory in the byte mode
Write Program Memory (Byte Mode)	0100 0000	XXXX 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4	A A A A A A A A A A A A A A A A A A A	D5 D5 D4 D3 D1	Write data to Program memory in the byte mode
Write Lock Bits <sup>(1)</sup>	1010 1100	1110 00盃 🖁	xxxx xxxx	xxxx xxxx	Write Lock bits. See Note 1.
Read Lock Bits	0010 0100	xxxx xxxx	xxxx xxxx	LB2 LB2 XXX	Read back current status of the lock bits (a programmed lock bit reads back as a "1")
Read Signature Bytes	0010 1000	A A 10 A 12 XXX A A 10 A 10 A 10 A A 10 A 10 A A 10 A A 10 A A 10 A A 10 A A 10 A A 10 A A 10 A A 10 A A 10	⊱xxx xxx0	Signature Byte	Read Signature Byte
Read Program Memory (Page Mode)	0011 0000	XXX 4 4 4 7 XXX A 4 9 9 9 9 9 9 9 9 9 9 9 9 9 9 9 9 9 9	Byte 0	Byte 1 Byte 255	Read data from Program memory in the Page Mode (256 bytes)
Write Program Memory (Page Mode)	0101 0000	XXXX 4 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7	Byte 0	Byte 1 Byte 255	Write data to Program memory in the Page Mode (256 bytes)

Note: 1. B1 = 0, B2 = 0 ---> Mode 1, no lock protection

B1 = 0, B2 = 1 ---> Mode 2, lock bit 1 activated

B1 = 1, B2 = 0 ---> Mode 3, lock bit 2 activated

B1 = 1, B1 = 1 ---> Mode 4, lock bit 3 activated

 $\underline{\text{Each}}$  of the lock bit modes needs to be activated sequentially before Mode 4 can be executed.

After Reset signal is high, SCK should be low for at least 64 system clocks before it goes high to clock in the enable data bytes. No pulsing of Reset signal is necessary. SCK should be no faster than 1/16 of the system clock at XTAL1.

For Page Read/Write, the data always starts from byte 0 to 255. After the command byte and upper address byte are latched, each byte thereafter is treated as data until all 256 bytes are shifted in/out. Then the next instruction will be ready to be decoded.

### 26. AC Characteristics

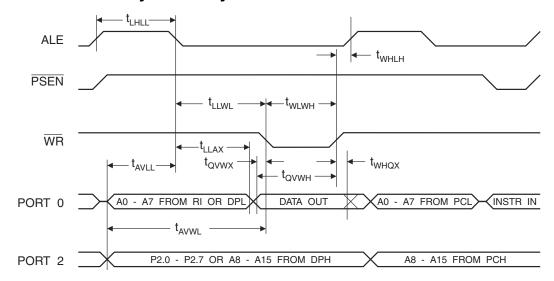
Under operating conditions, load capacitance for Port 0, ALE/ $\overline{PROG}$ , and  $\overline{PSEN}$  = 100 pF; load capacitance for all other outputs = 80 pF.

## 26.1 External Program and Data Memory Characteristics

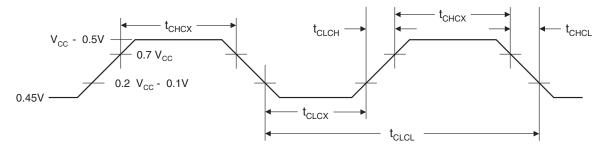
	Parameter	16 MHz	16 MHz Oscillator		Variable Oscillator	
Symbol		Min	Max	Min	Max	Units
1/t <sub>CLCL</sub>	Oscillator Frequency			0	16	MHz
t <sub>LHLL</sub>	ALE Pulse Width	85		2t <sub>CLCL</sub> -40		ns
t <sub>AVLL</sub>	Address Valid to ALE Low	22		t <sub>CLCL</sub> -40		ns
t <sub>LLAX</sub>	Address Hold After ALE Low	32		t <sub>CLCL</sub> -30		ns
t <sub>LLIV</sub>	ALE Low to Valid Instruction In		150		4t <sub>CLCL</sub> -100	ns
t <sub>LLPL</sub>	ALE Low to PSEN Low	32		t <sub>CLCL</sub> -30		ns
t <sub>PLPH</sub>	PSEN Pulse Width	142		3t <sub>CLCL</sub> -45		ns
t <sub>PLIV</sub>	PSEN Low to Valid Instruction In		82		3t <sub>CLCL</sub> -105	ns
t <sub>PXIX</sub>	Input Instruction Hold After PSEN	0		0		ns
t <sub>PXIZ</sub>	Input Instruction Float After PSEN		37		t <sub>CLCL</sub> -25	ns
t <sub>PXAV</sub>	PSEN to Address Valid	75		t <sub>CLCL</sub> -8		ns
t <sub>AVIV</sub>	Address to Valid Instruction In		207		5t <sub>CLCL</sub> -105	ns
t <sub>PLAZ</sub>	PSEN Low to Address Float		10		10	ns
t <sub>RLRH</sub>	RD Pulse Width	275		6t <sub>CLCL</sub> -100		ns
t <sub>WLWH</sub>	WR Pulse Width	275		6t <sub>CLCL</sub> -100		ns
t <sub>RLDV</sub>	RD Low to Valid Data In		147		5t <sub>CLCL</sub> -165	ns
t <sub>RHDX</sub>	Data Hold After RD	0		0		ns
t <sub>RHDZ</sub>	Data Float After RD		65		2t <sub>CLCL</sub> -60	ns
t <sub>LLDV</sub>	ALE Low to Valid Data In		350		8t <sub>CLCL</sub> -150	ns
t <sub>AVDV</sub>	Address to Valid Data In		397		9t <sub>CLCL</sub> -165	ns
t <sub>LLWL</sub>	ALE Low to RD or WR Low	137	239	3t <sub>CLCL</sub> -50	3t <sub>CLCL</sub> +50	ns
t <sub>AVWL</sub>	Address to RD or WR Low	122		4t <sub>CLCL</sub> -130		ns
t <sub>QVWX</sub>	Data Valid to WR Transition	13		t <sub>CLCL</sub> -50		ns
t <sub>QVWH</sub>	Data Valid to WR High	287		7t <sub>CLCL</sub> -150		ns
t <sub>WHQX</sub>	Data Hold After WR	13		t <sub>CLCL</sub> -50		ns
t <sub>RLAZ</sub>	RD Low to Address Float		0		0	ns
t <sub>WHLH</sub>	RD or WR High to ALE High	23	103	t <sub>CLCL</sub> -40	t <sub>CLCL</sub> +40	ns



## 29. External Data Memory Write Cycle



### 30. External Clock Drive Waveforms



### 31. External Clock Drive

Symbol	Parameter	Min	Max	Units
1/t <sub>CLCL</sub>	Oscillator Frequency	0	16	MHz
t <sub>CLCL</sub>	Clock Period	62.5		ns
t <sub>CHCX</sub>	High Time	20		ns
t <sub>CLCX</sub>	Low Time	20		ns
t <sub>CLCH</sub>	Rise Time		20	ns
t <sub>CHCL</sub>	Fall Time		20	ns

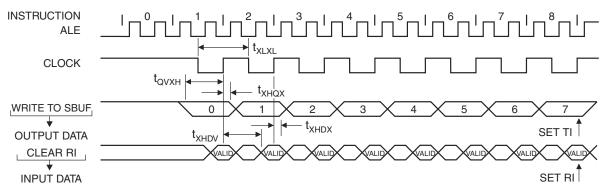


### 32. Serial Port Timing: Shift Register Mode Test Conditions

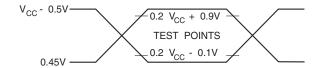
The values in this table are valid for  $V_{CC} = 2.7V$  to 4.0V and Load Capacitance = 80 pF.

		12 MH	łz Osc	Variable Oscillator		
Symbol	Parameter	Min	Max	Min	Max	Units
t <sub>XLXL</sub>	Serial Port Clock Cycle Time	1.0		12 t <sub>CLCL</sub>		μs
t <sub>QVXH</sub>	Output Data Setup to Clock Rising Edge	700		10 t <sub>CLCL</sub> -133		ns
t <sub>XHQX</sub>	Output Data Hold After Clock Rising Edge	50		2 t <sub>CLCL</sub> -80		ns
t <sub>XHDX</sub>	Input Data Hold After Clock Rising Edge	0		0		ns
t <sub>XHDV</sub>	Clock Rising Edge to Input Data Valid		700		10 t <sub>CLCL</sub> -133	ns

# 33. Shift Register Mode Timing Waveforms

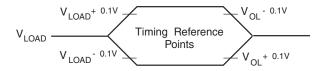


# 34. AC Testing Input/Output Waveforms<sup>(1)</sup>



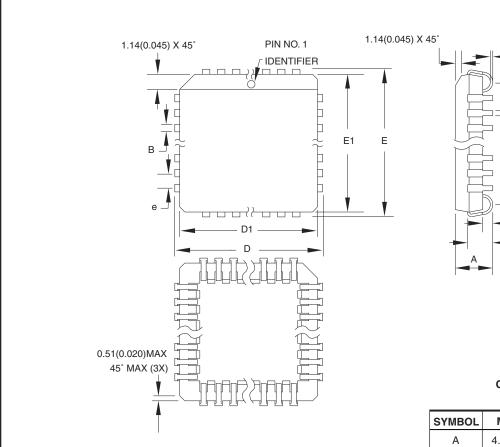
Note: 1. AC Inputs during testing are driven at  $V_{CC}$  - 0.5V for a logic 1 and 0.45V for a logic 0. Timing measurements are made at  $V_{IH}$  min. for a logic 1 and  $V_{IL}$  max. for a logic 0.

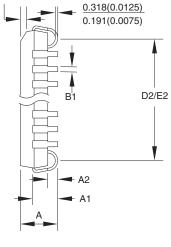
# 35. Float Waveforms<sup>(1)</sup>



Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V<sub>OH</sub>/V<sub>OL</sub> level occurs.

#### 37.2 44J





### **COMMON DIMENSIONS**

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
Α	4.191	_	4.572	
A1	2.286	_	3.048	
A2	0.508	_	_	
D	17.399	-	17.653	
D1	16.510	_	16.662	Note 2
E	17.399	_	17.653	
E1	16.510	_	16.662	Note 2
D2/E2	14.986	_	16.002	
В	0.660	_	0.813	
B1	0.330	_	0.533	
е	1.270 TYP			

Notes:

- 1. This package conforms to JEDEC reference MS-018, Variation AC.
- Dimensions D1 and E1 do not include mold protrusion.
   Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
- 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	44J, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	В





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